

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 166 | loc with encapsula\$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 16:41 |
| 2 | 111 | (loc with encapsula\$4) and (@ad<20000816) | USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 16:40 |
| 7 | 833 | 257/686.ccls. and (@ad<20000816) | USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 16:41 |
| 8 | 254 | (257/686.ccls. and (@ad<20000816)) and encapsula\$4 | USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 16:41 |

| | | | | |
|----|-----|--|---|------------------|
| 17 | 61 | ((chip or die) and (((remov\$3 or etch\$3 or delaminat\$3)and substrate)near encapsula\$4)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:17 |
| 18 | 0 | 4338/122. and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:00 |
| 20 | 136 | | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:07 |
| 21 | 196 | 257/707.ccls. and (encapsula\$) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:07 |
| 22 | 162 | (257/707.ccls. and (encapsula\$)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:36 |
| 23 | 294 | (chip or die) and ((fin\$2 or sink or spreader) near encapsula\$) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:17 |
| 24 | 225 | ((chip or die) and ((fin\$2 or sink or spreader) near encapsula\$)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:34 |
| 25 | 28 | (chip or die) and ((encapsula\$ and substrate) with (key or interlock\$3)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:39 |
| 26 | 16 | ((chip or die) and ((encapsula\$ and substrate) with (key or interlock\$3))) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:38 |
| 27 | 54 | (chip or die) and ((mold near cavity) with (key or interlock\$3)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:43 |
| 28 | 36 | loc same (mold near cavity) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:44 |

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|------------------|
| 1 | 366 | 438/4.ccls. and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:00 |
| 2 | 27 | (438/4.ccls. and (@ad<20000816)) and (encapsula\$) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:01 |
| 3 | 183 | 438/For.434.ccls. and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 12:43 |
| 4 | 1 | (438/For.434.ccls. and (@ad<20000816)) and (encapsula\$) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 14:34 |
| 5 | 116 | (flip near (chip or die)) and ((remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:54 |
| 7 | 1 | ("5677566").PN. | USPAT | 2003/02/19 12:49 |
| 6 | 75 | ((flip near (chip or die)) and ((remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:21 |
| 8 | 30 | (chip or die) and (laser near encapsula\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:24 |
| 9 | 26 | ((chip or die) and (laser near encapsula\$4)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:25 |
| 10 | 315 | (chip or die) and (laser with encapsula\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:25 |
| 11 | 240 | ((chip or die) and (laser with encapsula\$4)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:55 |
| 12 | 549 | 257/796.ccls. and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:50 |
| 13 | 7 | (257/796.ccls. and (@ad<20000816)) and ((laser or remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:53 |
| 14 | 2 | ((("6294830") or ("6251707"))).PN. | USPAT | 2003/02/19 13:53 |
| 15 | 2 | ((("20020027010") or ("20020027265"))).PN. | US-PGPUB | 2003/02/19 13:53 |
| 16 | 92 | (chip or die) and (((remov\$3 or etch\$3 or delaminat\$3)and substrate)near encapsula\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/02/19 13:55 |